

REMARKS/ARGUMENTS

In response to the Notice of Non-Compliant Amendment mailed February 13, 2008, Applicants incorporate the amendments as originally filed by Applicants on November 29, 2007, in addition to including proper markings in amended claim 21 as requested by the Examiner. No other changes have been made to the claims. All remarks included in Applicants' Amendment/Response filed November 29, 2007 have been included again, below, for the Examiner's convenience.

Reconsideration and allowance of the present application based on the following remarks are respectfully requested. Claims 1-2, 4, 6-17, and 21 have been amended. Claims 23-30 have been added. Support for all amendments and new claims can be found throughout the specification. No new matter has been added.

With respect to the 35 U.S.C. § 112, first and second paragraph, rejections, the amendments to the claims are believed to overcome these rejections. To the extent that the amendments to the claims do not directly address a particular rejection, Applicants respectfully assert that one of ordinary skill in the art would have a clear understanding of the metes and bounds of the claims. Accordingly, the claims are believed to be in full compliance with 35 U.S.C. § 112.

With respect to the 35 U.S.C. § 101 rejection, the amendment to claim 21 is believed to overcome this rejection.

Claims 14 -19 have been rejected under 35 U.S.C. § 102(b) as anticipated by U.S. Patent 5,176,956 ("Jevne"). Claims 1-22 have been rejected under 35 U.S.C. § 103(a) as obvious over U.S. Patent 5,234,996 ("Mori") in view of Jevne. Claims 8 and 22 have been rejected under 35 U.S.C. § 103(a) as obvious over Jevne. Claims 7 and 21-22 have been rejected under 35 U.S.C. § 103(a) as obvious over Jevne in view of Mori. The amendments to the claims are believed to place them in condition for allowance. Specifically, none of the cited references teach or suggest a moisture-curable liquid adhesive. To the contrary, Jevne teaches adhesives for biomedical use which are solid, exhibit tackiness, or which do not cure further once formed into their usable state. Similarly, Mori teaches a two component adhesive that, when combined prior to use, form an already-cured solid. As such, Applicants respectfully assert that the claims are patentable over the cited references.


Therefore, all objections and rejections having been addressed, it is respectfully submitted that the present application is in a condition for allowance and a Notice to that effect is earnestly solicited.

Should any issues remain unresolved, the Examiner is encouraged to contact the undersigned attorney for Applicants at the telephone number indicated below in order to expeditiously resolve any remaining issues.

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Respectfully submitted,

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